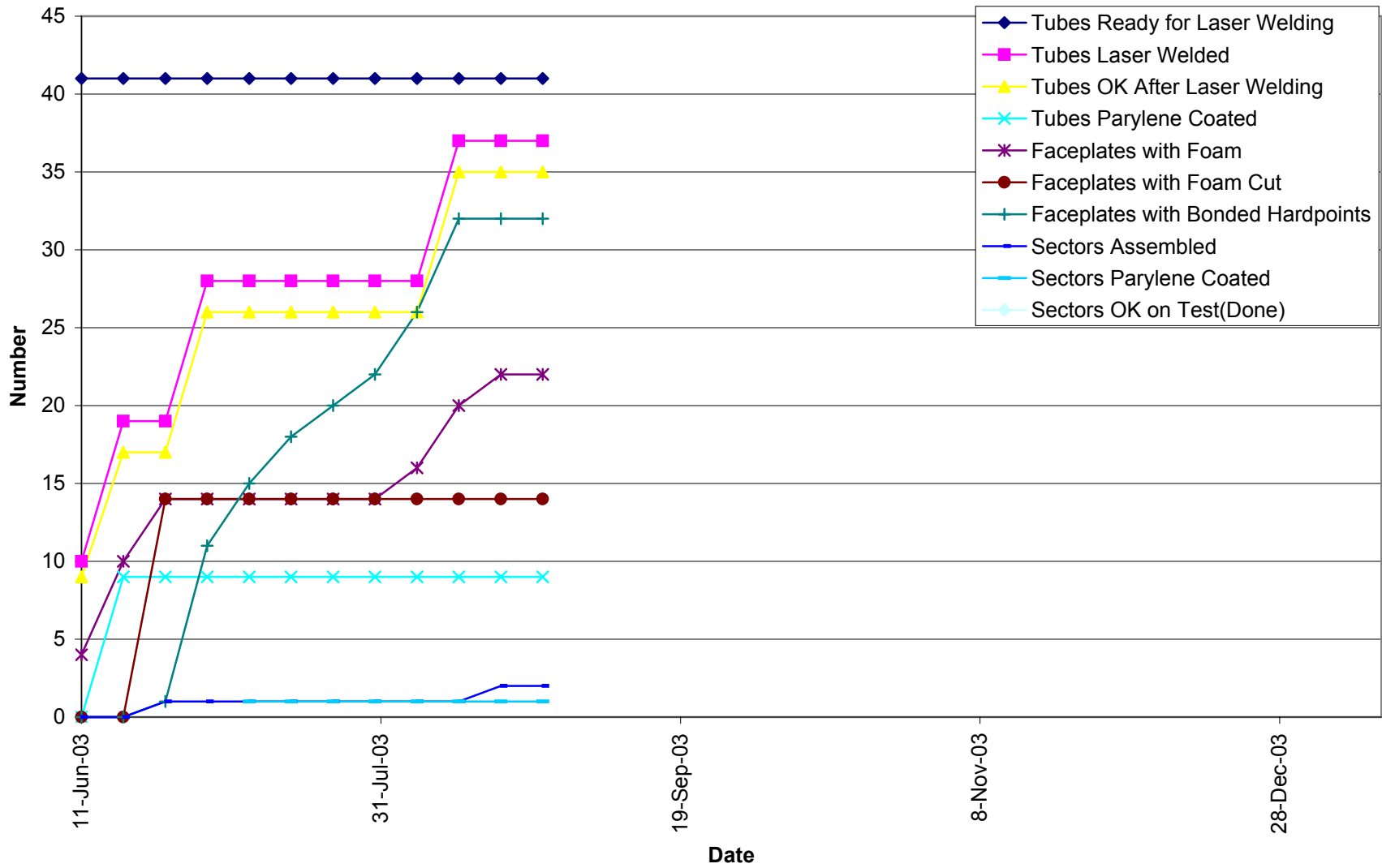


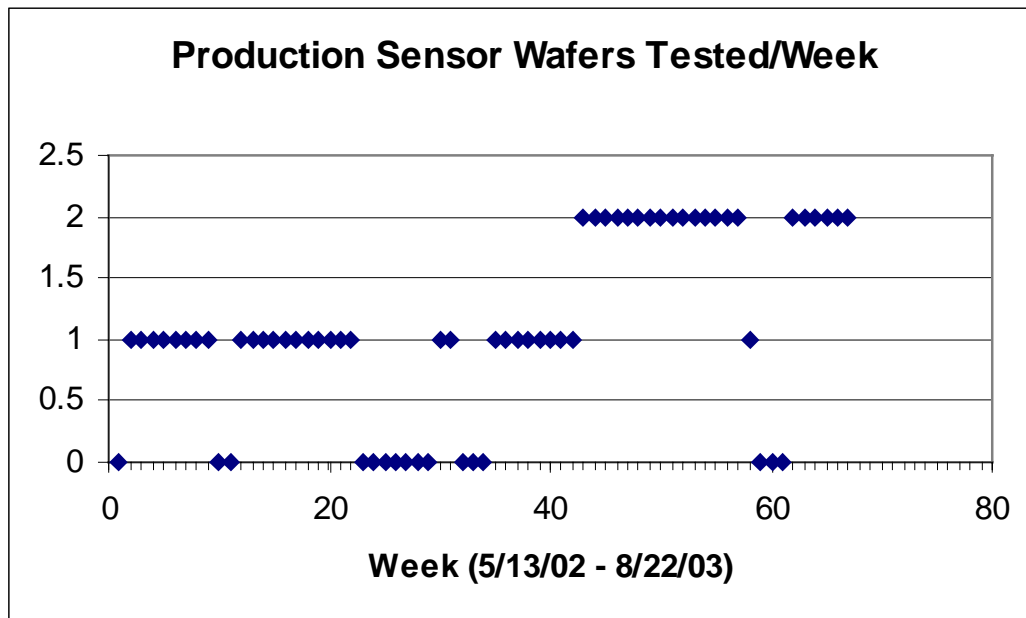
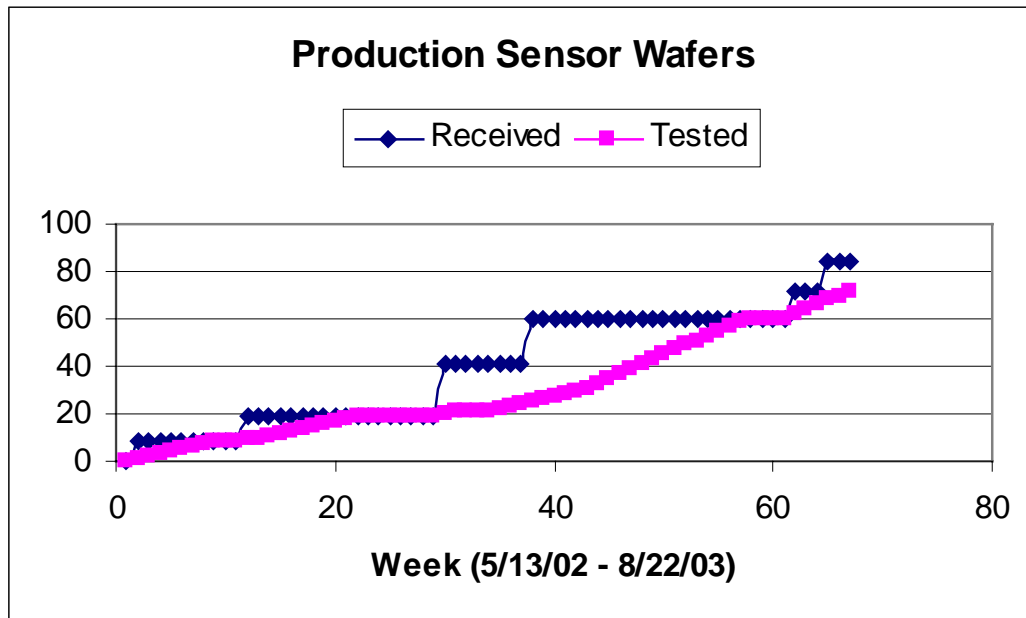
Disk Sector Production



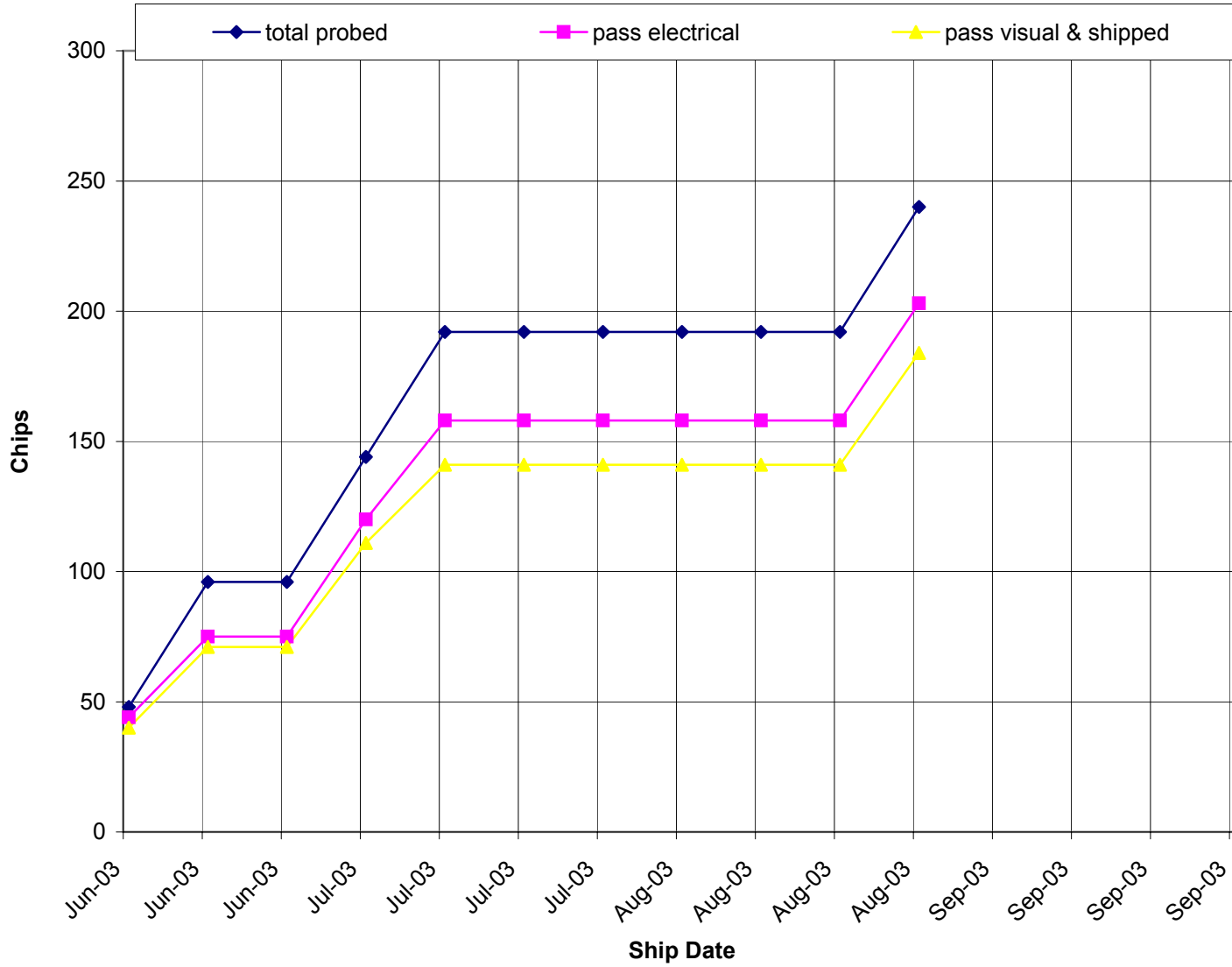
University Of New Mexico

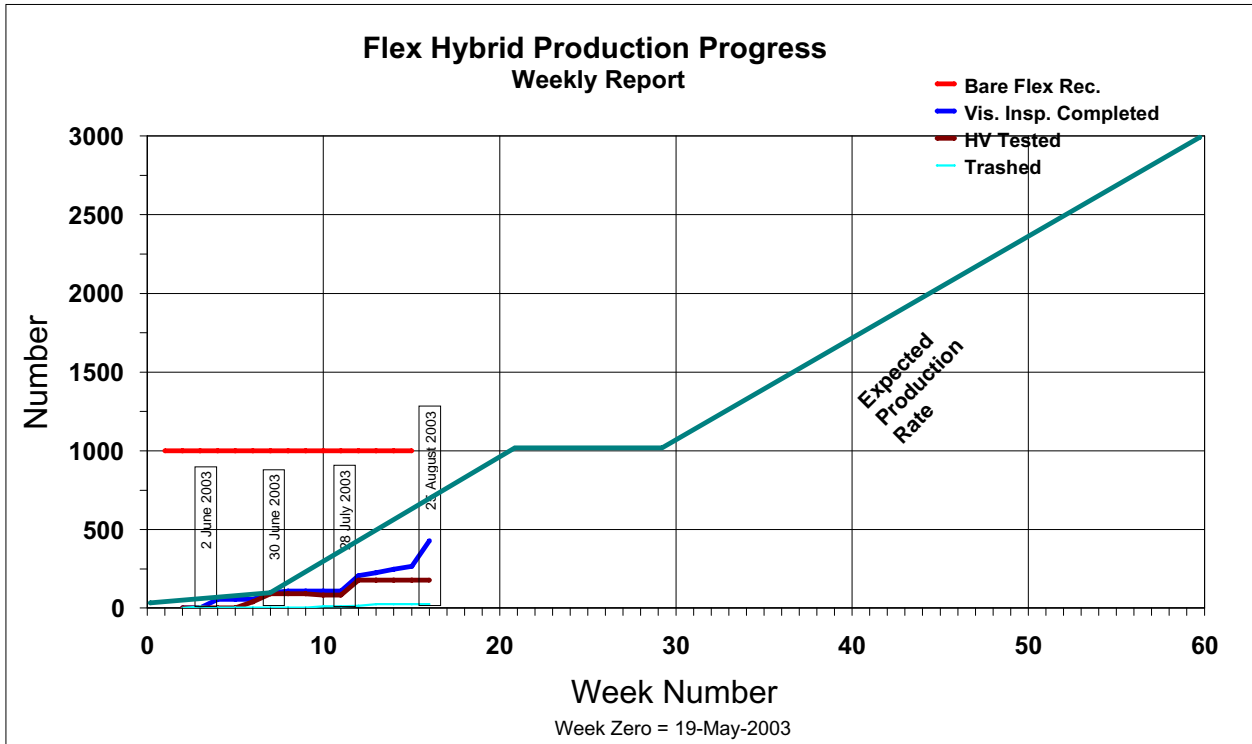
Sensor Wafer

Production Measurement Status



Production chip processing





Notes:
 Assembly sequence: Visual Inspection -> Component Loading -> HV Test -> MCC Attachment & Wire Bonding -> ready for Pitail Attachment and Module Construction
 Visual Inspection Completed refers to flex that are ready for component loading.
 HV Tested refers to flex hybrids that are ready for MCC attachment.
 Flex+MCC will be shown in a separate chart when MCC delivery rates are known.
 The above data includes only flex hybrids that are considered good.
 Trashed includes bad flex + flex that have been sacrificed for developmental purposes.
 Data is cumulative.

LBL Moudule FV5 Assembly

